

HAT1093C

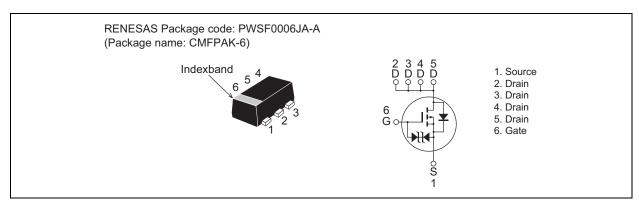
Silicon P Channel MOSFET Power Switching

REJ03G1230-0500 Rev.5.00 Jan 26, 2006

Features

- Low on-resistance $R_{DS(on)} = 41 \text{ m}\Omega \text{ typ. (at } V_{GS} = -4.5 \text{ V})$
- Low drive current.
- 1.8 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit | |
|--|---|-------------|------|--|
| Drain to Source voltage | V_{DSS} | -12 | V | |
| Gate to Source voltage | V _{GSS} | ±8 | V | |
| Drain current | I _D | -3 | А | |
| Drain peak current | I _D (pulse) ^{Note1} | -12 | A | |
| Body - Drain diode reverse drain current | I _{DR} | -3 | A | |
| Channel dissipation | Pch ^{Note 2} | 900 | mW | |
| Channel temperature | Tch | 150 | °C | |
| Storage temperature | Tstg | -55 to +150 | °C | |

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 $40 \times 40 \times 1.6$ mm), Ta = 25°C

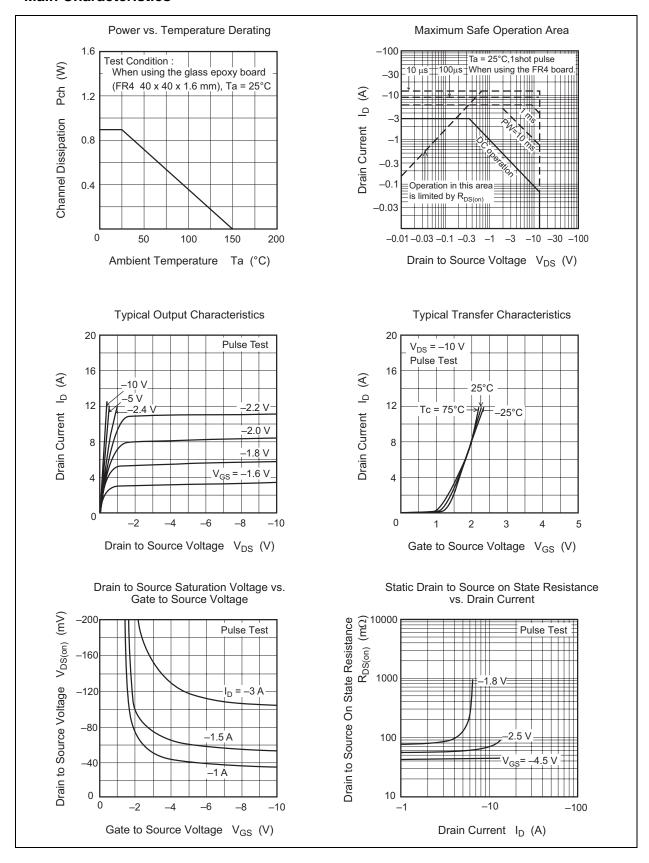
Electrical Characteristics

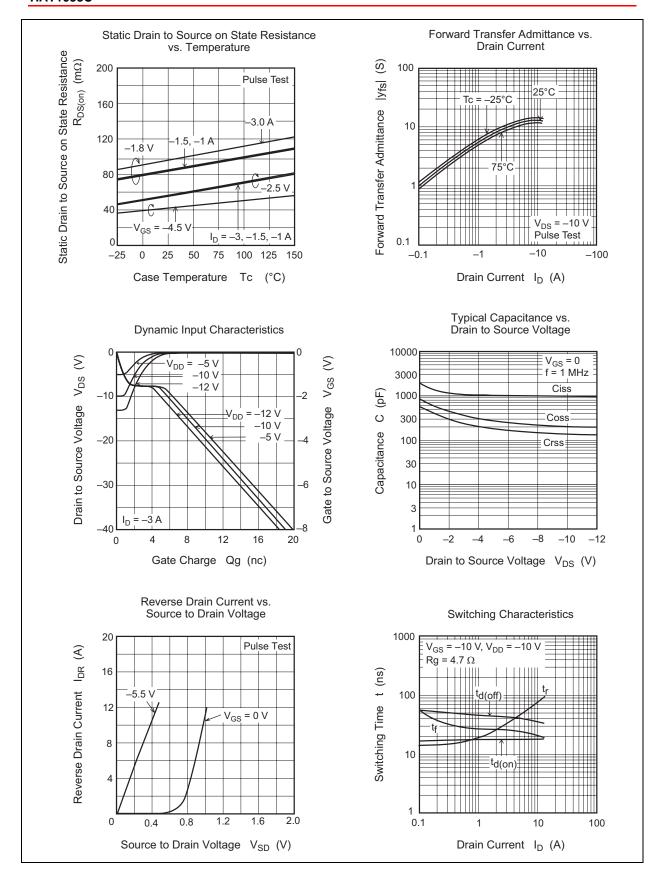
 $(Ta = 25^{\circ}C)$

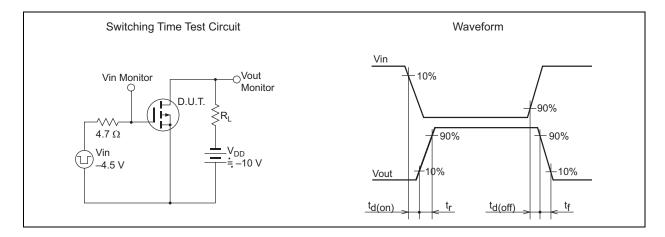
| Item | Symbol | Min | Тур | Max | Unit | Test Conditions | |
|-------------------------------------|---------------------|------|------|------|------|--|--|
| Drain to Source breakdown voltage | $V_{(BR)DSS}$ | -12 | _ | _ | V | $I_D = -10 \text{ mA}, V_{GS} = 0$ | |
| Gate to Source breakdown voltage | $V_{(BR)GSS}$ | ±8 | _ | _ | V | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$ | |
| Gate to Source leakage current | I _{GSS} | | _ | ±10 | μΑ | $V_{GS} = \pm 6.4V, V_{DS} = 0$ | |
| Drain to Source leakage current | I _{DSS} | | _ | -1 | μΑ | V _{DS} =-12 V, V _{GS} = 0 | |
| Gate to Source cutoff voltage | $V_{GS(th)}$ | -0.3 | _ | -1.2 | V | $I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note3}}$ | |
| Drain to Source on state resistance | R _{DS(on)} | _ | 41 | 54 | mΩ | $I_D = -1.5 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$ | |
| | | _ | 54 | 76 | mΩ | $I_D = -1.5 \text{ A}, V_{GS} = -2.5 \text{ V}^{\text{Note3}}$ | |
| | | _ | 85 | 128 | mΩ | $I_D = -1.5 \text{ A}, V_{GS} = -1.8 \text{ V}^{\text{Note3}}$ | |
| Forward transfer admittance | y _{fs} | 4 | 6.5 | _ | S | $I_D = -1.5 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$ | |
| Input capacitance | Ciss | _ | 940 | _ | pF | $V_{DS} = -10 \text{ V}, V_{GS} = 0,$ | |
| Output capacitance | Coss | _ | 200 | _ | pF | f = 1 MHz | |
| Reverse transfer capacitance | Crss | _ | 130 | _ | рF | | |
| Total gate charge | Qg | _ | 11 | _ | nC | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_{D} = -3 \text{ A}$ | |
| Gate to Source charge | Qgs | _ | 1.5 | _ | nC | | |
| Gate to Drain charge | Qgd | _ | 3.5 | _ | nC | | |
| Turn - on delay time | t _{d(on)} | _ | 18 | _ | ns | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$ | |
| Rise time | t _r | _ | 23 | _ | ns | $\begin{split} I_D = -1.5 \text{ A, } R_L = 6.7 \Omega, \\ R_g = 4.7 \Omega \end{split}$ | |
| Turn - off delay time | t _{d(off)} | _ | 50 | _ | ns | | |
| Fall time | t _f | _ | 28 | _ | ns | | |
| Body - Drain diode forward voltage | V_{DF} | _ | -0.8 | -1.1 | V | $I_F = -3 \text{ A}, V_{GS} = 0$ | |

Note: 3. Pulse test

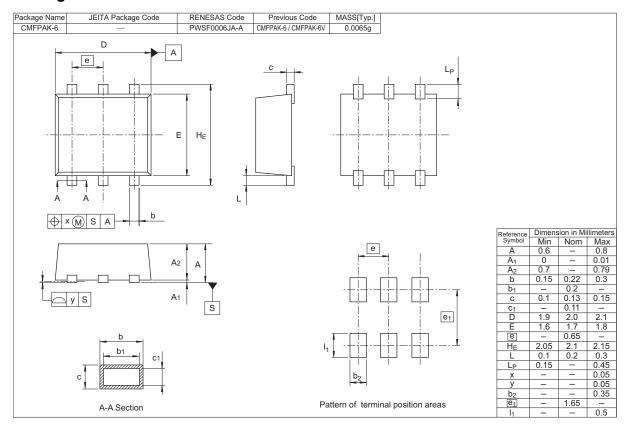
Main Characteristics







Package Dimensions



Ordering Information

| Part Name | Quantity | Shipping Container |
|---------------|----------|--------------------|
| HAT1093C-EL-E | 3000 pcs | Taping |

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